

| | | | | | | | | |
|---|----|--|-------------------------|---------------|--------------------------------------|----------|----------------------------|----|
| U.S. Department of Commerce, Patent and Trademark Office | | | | | Atty Docket No. | | Serial No. | |
| | | | | | M-7125-2D US | | Unknown | |
| INFORMATION DISCLOSURE STATEMENT BY APPLICANT | | | | | Applicant(s) | | | |
| (Use several sheets if necessary) | | | | | Mayer, OSteven T., Bhaskaran, Vijay; | | | |
| | | | | | Filing Date | | Group | |
| | | | | | Herewith | | Unknown | |
| U.S. Patent Documents | | | | | | | | |
| *Examiner Initial | | Document Number | Date | Name | Class | Subclass | Filing Date If Appropriate | |
| W | AA | 4,092,226 | 5/30/78 | Laing et al. | 204 | 51 | | |
| W | AB | 5,618,634 | 4/8/97 | Hosoda et al. | 428 | 610 | | |
| W | AC | 5,935,762 | 8/10/99 | Dai et al. | 430 | 312 | | |
| W | AD | 5,936,707 | 8/10/99 | Nguyen et al. | 355 | 18 | | |
| W | AE | 5,939,788 | 8/17/99 | McTeer | 257 | 751 | | |
| W | AF | 5,972,192 | 10/26/99 | Dubin et al. | 205 | 101 | | |
| W | AG | 6,099,711 | 8/8/00 | Dahms et al. | 205 | 101 | | |
| | AH | | | | | | | |
| | AI | | | | | | | |
| | AJ | | | | | | | |
| | AK | | | | | | | |
| Foreign Patent Documents | | | | | | | | |
| | | | | | | | Translation | |
| | | Document | Date | Country | Class | Subclass | Yes | No |
| | AL | | | | | | | |
| | AM | | | | | | | |
| OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.) | | | | | | | | |
| W | AN | <u>ULSI Technology</u> , Eds, C.Y. Chang and S.M. Sze (McGraw-Hill, 1996, pp. 444-445). | | | | | | |
| W | AO | <u>Electroplating</u> , Fredereick A. Lowenheim, , (McGraw-Hill, 1978, p 423). | | | | | | |
| W | AP | <u>Selective and Blanket Electroless Cu Plating Initiated by Contact Displacement...</u> , Valery M. Dubin, Yosi Shacham-Diamand and Bin Zhao, P.K. Vasudev, Chiu H. Ting, (VMIC Conf. June 26 & 27, 1995, pp 314-321). | | | | | | |
| W | AQ | <u>Copper Electroplating Process for Sub-Half-Micron ULSI Structures</u> , Robert J. Contolini, Lisa Tarte, Robert T. Graff, Lee B. Evans, J. Neal Cox, Marc R. Puich, Justin E. Gee, Xiao-Chun Mu, Chien Chiang, (VMIC Conf. June 27-29, 1995, pp. 322-325) | | | | | | |
| Examiner William Leader | | | Date Considered 12/2001 | | | | | |
| *EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant. | | | | | | | | |

USPTO
09/27/01
11/16/00